



T3 Towards eraHertz ransmissions

100Tb/s

10Tb/s 1Tb/s

100Gb/s

10Gb/s

1Gb/s 100Mb/s_{USB1}

10Mb/s 1Mb/s

100Kb/s

10Kb/s



BEAMS SCEE





Indoor

LTE Advanced

Outdoor: cellular (~100m)

2020

WEAN (~10m)

Wireless Roadmap

D2D: short range (<1m)

3G R99/EDGE

Wireless standards roadmap, from the ITRS (International Technology Roadmap for Semiconductors http://www.itrs2.net/)

2010

2015

2005



Context of T3 project

Wireless data traffic is growing by a factor of 100 every 10 years

It is estimated that the demand for data rate in wireless networks increases by 40% up to 70% year upon year

⇒ the wireless networks will need to deliver as much as several hundreds of times the capacity as compared to the current levels

To attain data rates of the order of 1 Tbps (or even some good fraction of it), a very broad bandwidth of several tens of GHz will be required.

Technical challenges for THz transmisions

- Electromagnetics: highly efficient & high-gain flat antennas
 - Compensating the huge path loss (102 dB at 300 GHz for a typical indoor distance of 10 m) by using very efficient and high-gain antennas
 - innovative flat antenna architectures must be invented
- Signal processing and digital communications
 - choice of the waveform (multi-carrier, single carrier, constant envelope)
 - the associated receivers (synchronization, channel estimation, equalization, etc.) and analog to digital design are considered as major bottlenecks
- Advanced materials, and fabrication / packaging technologies for THz systems
 - Due to the so-called THz gap, the standard fabrication streams and packaging techniques currently used at microwave frequencies (PCB, waveguides) and in optics (semi-conductors, thin film processes) are not suitable – or must evolve drastically
 - low-loss materials suitable for circuit and antenna design must be identified and characterized

Work done in T3 project

Antenna design (IETR/BEAMS with UC3M - Madrid)

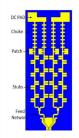
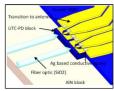
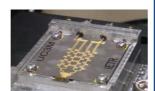


Photo-diode excited antennas



Thickness: 127 µm ε_r = 2.2 ; tan δ =0.003



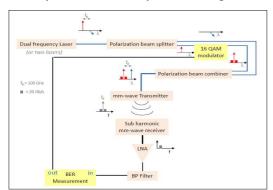
Optical power: 45 mW. Error-free data transmission:

- Bit rate: 2.15 Gbit/s (OOK)
- Distance: 25 cm

Dissemination:

- One seminar held at IETR (Sept. 2019): 30 attendees.
- 3 publications (2 at IRMMW-THZ 2019, 1 at Journées du Club Optique micro-ondes).

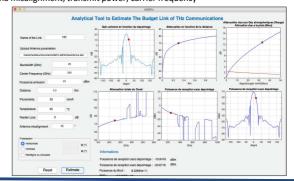
THz pre-testbed with optical carrier generation (FOTON)



Use of Persyst testbed (Lannion) to establish the performance

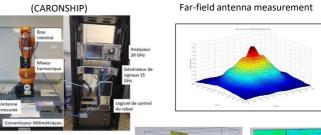
Link Budget in THz communications (IETR/SCEE)

Tool developed taking into account: path loss, humidity, pluviometry, Feeders losses, antenna misalignment, transmit power, carrier frequency



THz metrology (Lab-STICC)

Characterization device



Fresnel lens characterization:

